



Final Product Change Notification

202206013F01 : Maintaining Final Test Second Source Capability: ATTJ to ATTJ-B2 Qualification Results

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 15, 2022 **Effective date:** Sep 15, 2022

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Management summary

In order to maintain second source Final Test capability, NXP announces the qualification of NXP-ATTJ-B2 Tianjin, China replacing originally qualified NXP-ATTJ Tianjin, China. This ATTJ-B2 test site capability, along with the existing KESM Industries, Tianjin, China test site (no change), results in continued second source Final Test capability for the products associated with this notification. Slightly accelerated PCN Effective Date of 60 days is desired to mitigate against single source Final Test exposure.

Change Category

☐ Wafer Fab Process	☐ Assembly Process	☐ Product Marking	☐ Test Process	☐ Design
☐ Wafer Fab Materials	☐ Assembly Materials	☐ Mechanical Specification	☐ Test Equipment	☐ Errata
☐ Wafer Fab Location	☐ Assembly Location	☐ Packing/Shipping/Labeling	☒ Test Location	☐ Electrical spec./Test coverage
☐ Firmware	☐ Other			

PCN Overview

Description

Previously (April 2021), NXP Semiconductors announced with PCN 202104038F01 the relocation of NXP Final Test site ATTJ, Tianjin, China, to the nearby (2.5 km away) NXP Final Test site ATTJ-B2 Tianjin, China, creating a consolidated Test Center of Excellence with expanded floor space, since original ATTJ floor space was fully utilized.

In order to maintain second source Final Test capability for the products associated with this notification, NXP must now extend the original ATTJ test site qualification to the new ATTJ-B2 test site. This ATTJ-B2 test site capability, along with the existing KESM Industries, Tianjin, China test site (no change), results in continued second source Final Test capability.

NXP Semiconductors announces the successful qualification of ATTJ-B2 Tianjin, China Final Test site for the products associated with this notification. Many customers will recognize ATTJ-B2 through previous recently completed Final Test relocation qualification activities - and their granted approvals. The expectation is that this ATTJ-B2 qualification is a very streamlined activity, having built considerable customer confidence with the concluded ATTJ-B2 PCN 202104038F01 referenced above.

ATTJ-B2 is located 2.5 km Southeast from the current ATTJ main factory site, and adheres to the same ATTJ criteria: 100k clean room rating, temperature / humidity / ESD controls, and quality accreditations. All current ATTJ main factory Final Test equipment (hardware / software), test flows, test programs, policies, procedures, and personnel will be relocated to the new ATTJ-B2. Absolutely no impact to product form, fit, function or reliability.

Again, this new PCN 202206013F01 is simply to extend the previous NXP ATTJ Final Test qualification to the new NXP ATTJ-B2 Final Test facility, maintaining NXP's Final Test second source capability for supply assurance for the products associated with this notification.

Please see the attached documents for additional details, including Qualification Results.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-TF-01

Reason

Qualification of NXP-ATTJ-B2, Tianjin, China Final Test site is critical for product supply assurance – maintaining Final Test second source capability.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Not Applicable

Production

Planned first shipment Sep 15, 2022

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 14, 2022.

Related Notification

Notification	Issue Date	Effective Date	Title
202104038F01	Apr 28, 2021	May 28, 2021	NXP Final Test Site Relocation Initiative: ATTJ to ATTJ Building 2 (ATTJ-B2) - Phase 2 Qualification Results

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Brian Jiang
Position	Product Manager
e-mail address	brian.jiang@nxp.com

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NXP Quality Management Team.

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MC33660BEF	MC33797BPEW	MC33887PEK	MC34933EP
MC33660BEFR2	MC33797BPEWR2	MC33887PEKR2	MC34933EPR2
MC33662BJEF	MC33812EK	MC33887PFK	MC34972ATEK
MC33662BJEFR2	MC33812EKR2	MC33887PFKR2	MC34972ATEKR2
MC33662BLEF	MC33879APEK	MC33889BPEG	MC34972ATEW
MC33662BLEFR2	MC33879APEKR2	MC33889BPEGR2	MC34972ATEWR2
MC33662BSEF	MC33879BPEK	MC33889DPEG	MC34975ATEK
MC33662BSEFR2	MC33879BPEKR2	MC33889DPEGR2	MC34975ATEKR2
MC33662JEF	MC33879TEK	MC33897CTEF	MCZ33793AEF
MC33662JEFR2	MC33879TEKR2	MC33897CTEFR2	MCZ33793AEFR2
MC33662LEF	MC33880PEG	MC33972APEK	MCZ33793EF
MC33662LEFR2	MC33880PEGR2	MC33972APEKR2	MCZ33793EFR2
MC33662SEF	MC33880PEW	MC33972APEW	MCZ33800EK
MC33662SEFR2	MC33880PEWR2	MC33972APEWR2	MCZ33800EKR2
MC33689DPEW	MC33882PEK	MC33972ATEK	MCZ33810EK
MC33689DPEWR2	MC33882PEKR2	MC33972ATEKR2	MCZ33810EKR2
MC33730EK	MC33882PEP	MC33972ATEW	MCZ33897TEF
MC33730EKR2	MC33882PEPR2	MC33972ATEWR2	MCZ33897TEFR2
MC33742PEG	MC33882PVW	MC33972TEW	MCZ33996EK
MC33742PEGR2	MC33882PVWR2	MC33972TEWR2	MCZ33996EKR2
MC33742PEP	MC33883HEG	MC33975ATEK	MCZ33999EK
MC33742PEPR2	MC33883HEGR2	MC33975ATEKR2	MCZ33999EKR2
MC33742SPEG	MC33886PVW	MC33975TEK	MPC17510AEJ
MC33742SPEGR2	MC33886PVWR2	MC33975TEKR2	MPC17510AEJR2
MPC17511EP	MPC17529EJR2	MPC17531ATEP	MPC17C724EPR2
MPC17511EPR2	MPC17531ATEJ	MPC17531ATEPR2	MPC17C724EP
MPC17529EJ	MPC17531ATEJR2		

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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